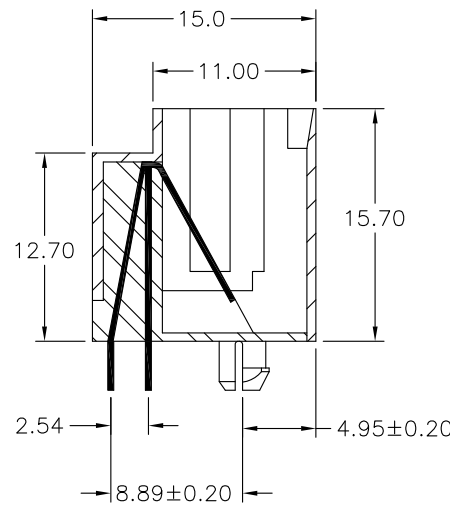
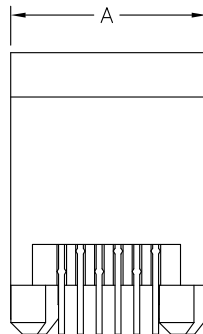
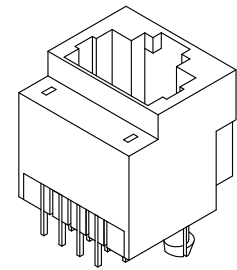
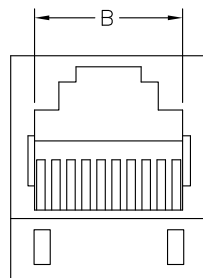


REV.	SPECIFICATION	ECN NO.	APPD.



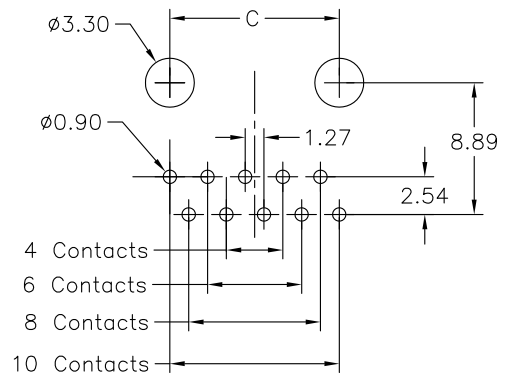
Material:

Housing: Thermoplastic Polyester Glass Filled UL94V-0.
Contacts: Copper Alloy.
Plating: Gold plated over Nickel on contact area ,
 Tin plated over Nickel on solder area .

Electrical Characteristics:

Current Rating: 1.5 AMP.
Insulator Resistance: 500MΩ min. at DC 500V.
Contact Resistance: 30mΩ max. at DC 100mA.
Operating Temperature: -40°C~+85°C.

***RoHS Compliant**



P.C. Board Layout

8949-H3	x	x	/06	B	N	A
Series	10: 10 Position	10: 10 Contacts	06: 0.6 μ" Gold Plated	B: Black	N: W/O Flange	A: Tray Package
	8: 8 Position	8: 8 Contacts	15: 15 μ" Gold Plated			
	6: 6 Position	6: 6 Contacts	30: 30 μ" Gold Plated			
	4: 4 Position	4: 4 Contacts	50: 50 μ" Gold Plated			
		2: 2 Contacts				

No. of Position	No. of contacts	Dimension		
		A	B	C
4	4	11.20	7.90	7.62
6	2/4/6	13.20	10.00	10.16
8	8	15.20	11.80	11.43
10	10	15.20	11.80	11.43

Tolerances	Dwg. No.	8949D02129	Title:
x = ±0.5	Projection		8949-H3 Series Modular Jack
.x = ±0.25	Unit	mm	
.xx = ±0.15	Scale	1:1	
	Drawn By	Peggy 05/31'12	①773

OUPIN
OUPIN ELECTRONIC(KUNSHAN) CO., LTD.
P/N: 8949-H3xx/06BNA

SHEET	1/1	Ver.No.	A2
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